

ON Semiconductor®

FDWS5360L-F085

N-Channel Power Trench® MOSFET **60V**, **60A**, **8.5m** Ω

Features

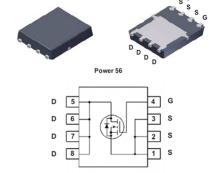
- Typ $r_{DS(on)}$ = 6.5m Ω at V_{GS} = 10V, I_D = 60A
- Typ $Q_{q(tot)}$ = 64nC at V_{GS} = 10V, I_D = 60A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101
- Wettable flanks for automatic optical inspection (AOI)

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Integrated Starter/alternator
- Primary Switch for 12V Systems







MOSFET Maximum Ratings $T_J = 25$ °C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage		60	V
V _{GS}	Gate to Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1) T _C = 25°C		60	^
ID	Pulsed Drain Current	T _C = 25°C	See Figure4	A
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	115	mJ
П	Power Dissipation		150	W
P_D	Derate above 25°C		1	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance Junction to Case		1	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient	(Note 3)	50	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDWS5360L	FDWS5360L-F085	Power 56	13"	12mm	3000 units

- 1: Current is limited by junction temperature.
- 2: Starting $T_J = 25^{\circ}C$, L = 0.1 mH, $I_{AS} = 48\text{A}$, $V_{DD} = 60\text{V}$ during inductor charging and $V_{DD} = 00\text{V}$ during time in avalanche 3: $R_{\theta,JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Units

Max

Тур

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Parameter

Off Characteristics								
B _{VDSS}	Drain to Source Breakdown Voltage	I _D = 250μA, \	/ _{GS} = 0V	60	-	-	V	
l	Drain to Source Leakage Current	V _{DS} =60V,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	-	1	μΑ	
DSS		$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA	
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA	

Test Conditions

Min

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		1.0	1.9	3.0	V
	Drain to Source On Resistance	I _D = 60A,	$T_{J} = 25^{\circ}C$	-	6.5	8.5	$m\Omega$
_		V _{GS} = 10V	$T_J = 175^{\circ}C(Note 4)$	-	14.3	17.5	$m\Omega$
r _{DS(on)}		I _D = 60A,	$T_{J} = 25^{\circ}C$	-	8.7	10.5	mΩ
		V _{GS} = 4.5V	$T_J = 175^{\circ}C(Note 4)$	-	18.2	21.6	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 30V, V _{GS} = 0V, f = 1MHz		-	3695	-	pF
C _{oss}	Output Capacitance			-	295	-	pF
C _{rss}	Reverse Transfer Capacitance			-	155	-	pF
R_g	Gate Resistance	f = 1MHz		-	1.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0 \text{ to } 10V$ $V_{GS} = 0 \text{ to } 2V$ $V_{DD} = 48V$ $I_{D} = 60A$		-	64	72	nC
Q _{g(th)}	Threshold Gate Charge			-	6.5	7.8	nC
Q_{gs}	Gate to Source Gate Charge			-	13.8	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			ı	13.5	-	nC

Switching Characteristics

t _{on}	Turn-On Time	V_{DD} = 30V, I_{D} = 60A, V_{GS} = 10V, R_{GEN} = 6 Ω	-	-	40	ns
t _{d(on)}	Turn-On Delay Time		-	22	-	ns
t _r	Rise Time		-	14	-	ns
t _{d(off)}	Turn-Off Delay Time		-	79	-	ns
t _f	Fall Time		-	16	-	ns
t _{off}	Turn-Off Time		-	-	104	ns

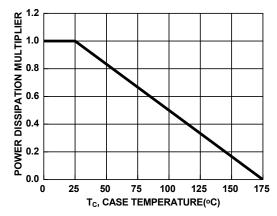
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	I _{SD} = 60A, V _{GS} = 0V	-	-	1.25	V
T _{rr}	Reverse Recovery Time	$I_F = 60A$, $dI_{SD}/dt = 100A/\mu s$,	-	36	41	ns
Q _{rr}	Reverse Recovery Charge	V _{DD} =48V	-	36	45	nC

Notes

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



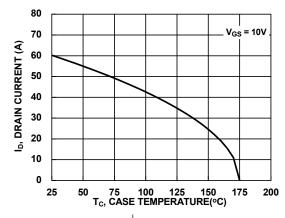


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

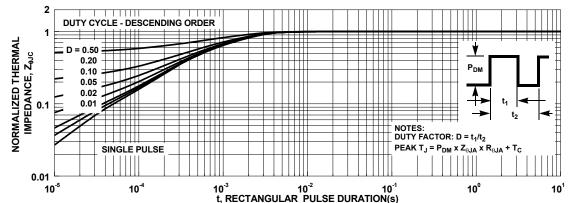


Figure 3. Normalized Maximum Transient Thermal Impedance

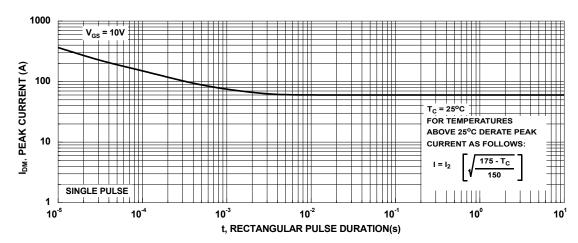


Figure 4. Peak Current Capability

Typical Characteristics

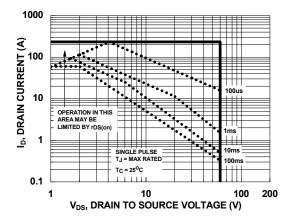
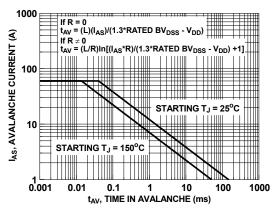


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

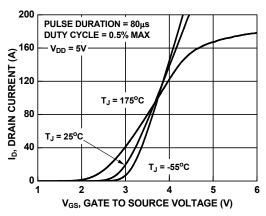


Figure 7. Transfer Characteristics

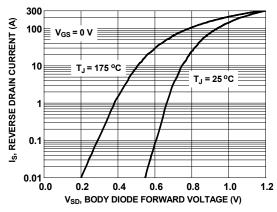


Figure 8. Forward Diode Characteristics

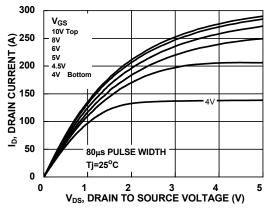


Figure 9. Saturation Characteristics

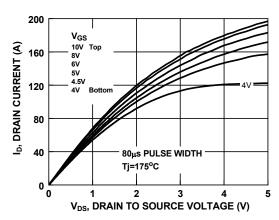


Figure 10. Saturation Characteristics

Typical Characteristics

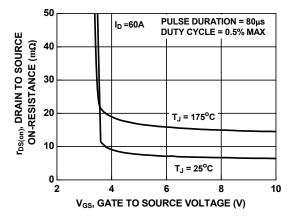


Figure 11. Rdson vs Gate Voltage

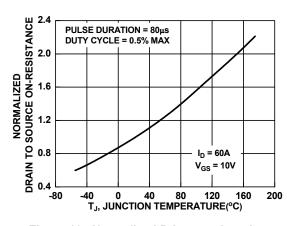


Figure 12. Normalized Rdson vs Junction Temperature

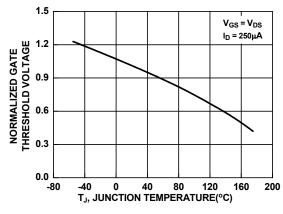


Figure 13. Normalized Gate Threshold Voltage vs
Temperature

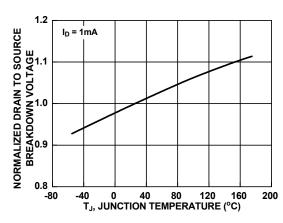


Figure 14. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

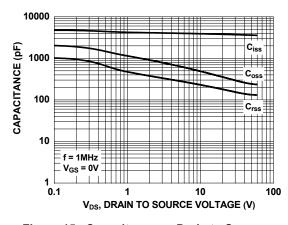


Figure 15. Capacitance vs Drain to Source Voltage

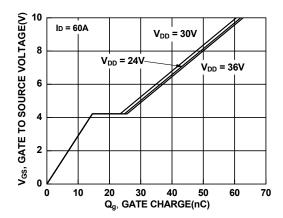


Figure 16. Gate Charge vs Gate to Source Voltage

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative